WHAT IS CLAIMED IS:

1. A thin metal layers-having ceramic green sheet comprising:

a base film;

a first thin metal layer formed on the whole surface of said base film;

a second thin metal layer formed on said first thin metal layer in the form of predetermined pattern; and

a ceramic powder-dispersed layer, comprising a binder and a ceramic powder dispersed therein, and being formed on the first thin metal layer surface including the second thin metal layer surface.

2. The thin metal layers-having ceramic green sheet according to claim 1, which further comprises a resin layer interposed between said base film and said first thin metal layer.

3. The thin metal layers-having ceramic green sheet according to claim 2, wherein said resin layer comprises a material substantially the same as the binder of said ceramic powder-dispersed layer.

4. The thin metal layers-having ceramic green sheet according to claim 1, wherein said first thin metal layer has a thickness of 0.001 to 1.0 μm.

5. The thin metal layers-having ceramic green sheet according to claim 1, wherein said second thin metal layer has a thickness of twice or more that of the first thin metal layer.

6. The thin metal layers-having ceramic green sheet according to claim 1, wherein said first thin metal layer is formed by a vacuum film formation process.

7. The thin metal layers-having ceramic green sheet according to claim 1, wherein said second thin metal layer is formed by electrolytic plating.

8. A method for producing a ceramic capacitor comprising the steps of:

preparing a plurality of the thin metal layers-having ceramic green sheets according to claim 1;

peeling the base film of one of said plurality of thin metal layers-having ceramic green sheets;

superposing another thin metal layers-having ceramic green sheet on said base film-peeled ceramic green sheet

by bringing the ceramic powder-dispersed layer of said another ceramic green sheet into contact with the first thin metal layer or resin layer of said base film-peeled ceramic green sheet;

repeating said peeling step and said superposing step predetermined times to form a laminated product of said plurality of ceramic green sheets; and

burning said laminated product.

9. The thin metal layers-having ceramic green sheet according to claim 3, wherein said first thin metal layer has a thickness of 0.001 to 1.0 μm.

10. The thin metal layers-having ceramic green sheet according to claim 3, wherein said second thin metal layer has a thickness of twice or more that of the first thin metal layer.

11. The thin metal layers-having ceramic green sheet according to claim 3, wherein said first thin metal layer is formed by a vacuum film formation process.

12. The thin metal layers-having ceramic green sheet according to claim 3, wherein said second thin metal layer is formed by electrolytic plating.

13. The method for producing a ceramic capacitor according to claim 8, wherein said plurality of thin metal layers-having ceramic green sheets further comprise a resin layer interposed between said base film and said first thin metal layer, and said resin layer comprises a material substantially the same as the binder of said ceramic powder-dispersed layer.